



PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Pre Amended  
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Revised  
11/9/01

In re application of

Honchin EN, et al.

Appln. No.: 09/787,139

Confirmation No.: 6279

Group Art Unit: 2836

Filed: March 14, 2001

Examiner: Unassigned

For: PRINTED WIRING BOARD AND ITS MANUFACTURING METHOD

**SECOND PRELIMINARY AMENDMENT**

Commissioner for Patents  
Washington, D.C. 20231

Sir:

Prior to examination, please amend the above-identified application as follows:

**IN THE CLAIMS:**

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**The claims are amended as follows:**

31. (amended) The process for manufacturing a multilayer printed circuit board according to claim 27, wherein, in the step for thinning the copper foil of said copper-clad laminate by etching, the thickness of the copper foil is reduced to 1 to 10  $\mu\text{m}$ .

**Claim 47 is added as a new claim.**

47. (new) The process for manufacturing a multilayer printed circuit board according to claim 28, wherein, in the step for thinning the copper foil of said copper-clad laminate by etching, the thickness of the copper foil is reduced to 1 to 10  $\mu\text{m}$ .

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